L Number	Hits	Search Text	DB	Time stamp
1	3	(semiconductor adj substrate) and (glass	USPAT;	2004/10/18 09:06
		adj substrate) and ((conductive adj plug)	US-PGPUB;	
1		with insulat\$)	EPO; JPO;	
			DERWENT;	
1	1.0	//	IBM_TDB	2004/10/10 00:11
3	18	((conductive adj plug) with insulat\$) and	USPAT; US-PGPUB;	2004/10/18 09:11
		imaging	EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1	((conductive adj plug) with insulat\$) and	USPĀT;	2004/10/18 09:11
		imager	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
ا ا	27	//	IBM_TDB	2004/10/10 00:17
5	77	((conductive adj plug) with insulat\$) and optical	USPAT; US-PGPUB;	2004/10/18 09:17
		Opercar	EPO; JPO;	. 1
			DERWENT;	
			IBM TDB	
6	19	((conductive adj plug) with oxide) and	USPĀT;	2004/10/18 09:17
	•	optical	US-PGPUB;	
			EPO; JPO;	
[			DERWENT;	
7	6	(/conductive add mlum) with and all and	IBM_TDB	2004/10/18 09:18
′	0	((conductive adj plug) with oxide) and imaging	USPAT; US-PGPUB;	2004/10/18 09:18
		imaging	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	2	((conductive adj plug) with oxide) and	USPAT;	2004/10/18 09:18
		imager	US-PGPUB;	,
	•		EPO; JPO;	
			DERWENT;	
9	152	((conductive adj material) with oxide) and	IBM_TDB USPAT;	2004/10/18 09:19
	. 132	imager	US-PGPUB;	2004/10/10 09:19
			EPO; JPO;	
		·	DERWENT;	
	_		IBM_TDB	
10	0	((conductive adj material) with oxide with	USPAT;	2004/10/18 09:19
		(through adj hole)) and imager	US-PGPUB; EPO; JPO;	
l			DERWENT;	
			IBM TDB	
11	0	((conductive adj material) with oxide with	USPAT;	2004/10/18 09:19
		(hole)) and imager	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
12	3	//gonductive add material) with swide with	IBM_TDB	2004/10/10 00:00
14	3	((conductive adj material) with oxide with (via)) and imager	USPAT; US-PGPUB;	2004/10/18 09:20
		(via), and imager	EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
13	· 9	((conductive adj material) with oxide with	USPAT;	2004/10/18 09:20
		(via)) and imaging	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
14	30	((conductive adj material) with oxide with	IBM_TDB USPAT;	2004/10/18 09:51
- •	50	(via)) and optical	US-PGPUB;	2004/10/10 09.31
		· · · · · · · · · · · · · · · · · · ·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16 .	10	(imaging adj device) and (reinforce\$ near	USPAT;	2004/10/18 09:54
		plate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
LI			1 TDM_1 DD	

17	26	<pre>(imaging adj device) and (reinforce\$ near (layer or film))</pre>	USPAT; US-PGPUB; EPO; JPO;	2004/10/18 09:58
19	15	(imaging adj device) with reinforce\$	DERWENT; IBM_TDB USPAT;	2004/10/18 09:58
		(Imaging adj device, with Termiorce)	US-PGPUB; EPO; JPO;	2004/10/10 03:30
-	6	(solid adj state adj imaging adj device)	DERWENT; IBM_TDB USPAT;	2004/09/28 10:07
		and translucent and (through adj hole) and terminal	US-PGPUB; EPO; JPO; DERWENT;	
-	17	(imaging adj device) and translucent and (through adj hole) and terminal	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/24 13:13
			DERWENT; IBM_TDB	
_	106	(imaging adj device) and translucent and (via) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/24 13:20
-	59	(imaging adj device) and translucent and (hole) and terminal	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/27 19:30
_	6	(solid adj state adj imaging adj device)	DERWENT; IBM_TDB USPAT;	2004/09/28 10:06
		and translucent and (semiconductor adj substrate)	US-PGPUB; EPO; JPO; DERWENT;	
<b>-</b>	725	(solid adj state adj imaging adj device) and (semiconductor adj substrate)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/24 13:25
-	18	(solid adj state adj imaging adj device) and (semiconductor adj substrate) and (external adj terminal)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/27 15:54
-	20	(solid adj state adj imaging adj device) and (semiconductor adj substrate) and (glass adj substrate)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/27 19:09
-	92	(imaging adj device) and (semiconductor adj substrate) and (glass adj substrate)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/27 17:11
-	1	(imaging adj device) and ((hole or via or plug) adj semiconductor adj substrate) and (glass adj substrate)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/27 17:12
_ ·	0	(imaging adj device) and ((hole or via or plug) adj semiconductor adj substrate) and (transparent adj substrate)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/27 17:13
_	1		DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/09/27 17:13
		(translucent adj substrate)	EPO; JPO; DERWENT; IBM TDB	

-	2	(imaging adj device) and ((hole or via or	USPAT;	2004/09/27 17:13
		plug) near (semiconductor adj substrate))	US-PGPUB;	
		and (translucent adj substrate)	EPO; JPO;	
			DERWENT;	
	_	l	IBM_TDB	
_	5	(	USPAT;	2004/09/27 17:14
		plug) near (substrate)) and (translucent	US-PGPUB;	1
		adj substrate)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	6	(	USPAT;	2004/09/27 17:18
İ		plug) with (substrate)) and (translucent	US-PGPUB;	
		adj substrate)	EPO; JPO;	
			DERWENT;	
	295	257/89.ccls.	IBM_TDB   USPAT;	2004/09/27 17:37
	293	257765.0015.	US-PGPUB;	2004/09/21 17:37
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	1600	257/59.ccls.	USPAT;	2004/09/27 18:04
	1000	2017 031 00251	US-PGPUB;	2004/03/2/ 10:04
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	109	257/59.ccls. and (semiconductor adj	USPAT;	2004/09/27 17:39
		substrate) and (glass adj substrate)	US-PGPUB;	=====================================
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1498	257/72.ccls.	USPAT;	2004/09/27 17:51
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	121		USPAT;	2004/09/27 17:55
		substrate) and (glass adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
_	595	257/434.ccls.	IBM_TDB USPAT;	2004/09/27 18:04
		237/434.0013.	US-PGPUB;	2004/09/2/ 18:04
		· ·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	6	257/434.ccls. and (semiconductor adj	USPAT;	2004/09/27 18:06
		substrate) and (glass adj substrate)	US-PGPUB;	2001, 03, 2. 10.00
1			EPO; JPO;	
	İ		DERWENT;	
			IBM TDB	
-	93	257/460.ccls.	USPAT;	2004/09/27 19:18
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	3	, , , , , , , , , , , , , , , , , , , ,	USPĀT;	2004/09/27 18:06
1	1	substrate) and (glass adj substrate)	US-PGPUB;	
]	1		EPO; JPO;	_
]	İ		DERWENT;	·
	1.05	257/4621-	IBM_TDB	0004/00/07 == ==
_	465	257/462.ccls.	USPAT;	2004/09/27 18:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	)	257/462.ccls. and (semiconductor adj	IBM_TDB USPAT;	2004/09/27 18:41
	-	substrate) and (glass adj substrate)	US-PGPUB;	2004/03/2/ 10:41
		described and (grade ad) substrate/	EPO; JPO;	
	İ		DERWENT;	
			IBM TDB	,
<u> </u>				<u> </u>

	1385		USPAT;	2004/09/27 19:11
		adj substrate) and display and image	US-PGPUB;	
			EPO; JPO;	
İ			DERWENT;	
<u> </u>	663	through adi holo adi formed adi gubetrate	IBM_TDB   USPAT;	2004/09/28 06:37
-	003	through adj hole adj formed adj substrate	US-PGPUB;	2004/09/28 00.37
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	
_	45	through adj hole adj formed adj	USPĀT;	2004/09/27 19:12
		semiconductor adj substrate	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	250	348/340.ccls.	USPAT;	2004/09/27 19:18
		·	US-PGPUB;	
			EPO; JPO;	ļ
			DERWENT;	
			IBM_TDB	
-	0	translucent adj member adj formed adj	USPAT;	2004/09/27 19:31
		substrate	US-PGPUB;	
	l .		EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/07 10 00
-	1	transparent adj member adj formed adj	USPAT;	2004/09/27 19:32
		substrate	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	268	transparent near (formed adj substrate)	USPAT;	2004/09/27 19:32
	200	cransparent near (ronmed adj substrace)	US-PGPUB;	2004/03/27 13:32
			EPO; JPO;	
			DERWENT;	<u>`</u>
			IBM TDB	
-	5	translucent near (formed adj substrate)	USPĀT;	2004/09/27 19:33
1			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	628	glass near (formed adj substrate)	USPAT;	2004/09/27 19:33
]		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1	07	(*h	IBM_TDB	2004/00/00 00 55
-	87	(through adj hole adj formed adj	USPAT;	2004/09/28 06:57
		substrate) and (imager or imaging or display or photodiode)	US-PGPUB;	
		disping of photonione;	EPO; JPO; DERWENT;	
			IBM TDB	
_	256	(hole adj formed adj substrate) and	USPAT;	2004/09/28 06:59
	233	(imager or imaging or display or	US-PGPUB;	=====================================
		photodiode)	EPO; JPO;	
		<u>'</u>	DERWENT;	
			IBM TDB	
-	162	438/75.ccls.	USPĀT;	2004/09/28 07:04
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
_	728	438/73.ccls.	USPAT;	2004/09/28 07:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	210	438/73.ccls. and (imager or imaging or	IBM_TDB	2004/09/28 07:21
	210	438//3.ccis. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB;	2004/09/20 0/:21
1		alberty of photouroue)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
L				<del> </del>

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_	17	257/252.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 07:34
			DERWENT; IBM_TDB	
-	32	257/253.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 07:37
	101	257/4141	DERWENT; IBM_TDB	2004/09/28 07:43
-	101	257/414.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/28 07:43
-	1252	257/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj substrate) and (imager or	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/28 08:39
		imaging or display or photodiode)	DERWENT; IBM_TDB	
_	28	257/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/28 08:46
-	19	438/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or	IBM_TDB USPAT; US-PGPUB;	2004/09/28 08:50
		translucent) adj member) and (imager or imaging or display or photodiode)	EPO; JPO; DERWENT; IBM_TDB	
-	6	348/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 09:11
_	4	((glass or transparent or translucent) adj member) near (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/28 09:13
-	560	((glass or transparent or translucent) near (semiconductor adj substrate)) and (imager or imaging or display or photodiode)	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 09:15
-	1039	(solid adj state adj imaging adj device) and (translucent or glass or transparent)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/28 10:38
-	125	(solid adj state adj imaging adj device) and (quartz)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/28 10:39
-	0	351997.FREF.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/30 08:55
_	0	0351997.FREF.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/09/30 08:55
			EPO; JPO; DERWENT; IBM TDB	·
-	1	2001351997.FREF.	USPAT; US-PGPUB; EPO; JPO;	2004/09/30 08:57
			DERWENT; IBM_TDB	

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<b>-</b>	0	2001351997.FRPD.	USPAT;	2004/09/30 08:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	351997.FRPD.	IBM_TDB USPAT;	2004/09/30 08:56
		331997.FRFD.	US-PGPUB;	2004/03/30 00:30
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
_	1	173845.FREF.	USPAT;	2004/09/30 08:57
			US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
		·	IBM_TDB	
-	0	2000173845.FREF.	USPAT;	2004/09/30 08:57
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	, ,
-	1	173845.FRPN.	USPAT;	2004/09/30 09:05
			US-PGPUB;	
		· ·	EPO; JPO;	
			DERWENT;	
_	0	   fumio-hata.in.	IBM_TDB USPAT;	2004/09/30 09:08
-		Lumio-naca.in.	US-PGPUB;	2004/03/30 03:08
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	l 0	fumi-hat\$.in.	USPAT;	2004/09/30 09:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
			IBM_TDB	
-	0	fumi-ha\$.in.	USPĀT;	2004/09/30 09:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	0	fumi-h\$.in.	USPAT;	2004/09/30 09:08
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
1_	10	fumio-h\$.in.	IBM_TDB USPAT;	2004/09/30 09:09
	"	LOWING HASTIL	US-PGPUB;	2004/03/30 03:03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	fumio-hata.in.	USPAT;	2004/09/30 09:10
			US-PGPUB;	
			EPO; JPO;	
	i		DERWENT;	
			IBM_TDB	
-	1	fumio-hat\$.in.	USPAT;	2004/09/30 09:10
			US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
_	30	(reinforgement add plate) and (place add	IBM_TDB	2004/10/16 10 00
-	30	(reinforcement adj plate) and (glass adj substrate)	USPAT; US-PGPUB;	2004/10/16 18:03
		SUDSCIACE;	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	(reinforcement adj plate) and (solid adj	USPAT;	2004/10/16 18:04
		state adj imaging adj device)	US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
			IBM TDB	

	<del></del>	· · · · · · · · · · · · · · · · · · ·		
-	5	(reinforcement adj plate) and (imaging adj	USPAT;	2004/10/16 18:11
		device)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	57	(=== == (====== ==) =====,	USPAT;	2004/10/16 18:37
		adj device) and (through adj hole)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	161	(sio or (silicon adj oxide)) and (optical	USPĀT;	2004/10/16 18:38
1		adj element) and (through adj hole)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	49	((sio or (silicon adj oxide)) with via)	USPAT;	2004/10/16 18:34
		and (optical adj element)	US-PGPUB;	
		-	EPO; JPO;	
			DERWENT;	
	-		IBM TDB	
_	35	((sio or (silicon adj oxide)) with via)	USPĀT;	2004/10/16 18:34
		and (imaging adj device)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
-	55	(sio or (silicon adj oxide)) and (imaging	USPAT;	2004/10/16 18:38
		adj device) and (through adj hole) and	US-PGPUB;	
		thickness	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	23	((sio or (silicon adj oxide)) with	USPĀT;	2004/10/16 18:38
		thickness) and (optical adj element) and	US-PGPUB;	
		(through adj hole)	EPO; JPO;	
1			DERWENT;	
			IBM TDB	